

WHAT IS CLAIMED IS

1. An electronic device having:
a body having a pair of terminal electrodes and
an interposer board to a front surface of which the
pair of terminal electrodes are connected and having on its
back surface a pair of external electrodes electrically
connected to the parts where the pair of terminal electrodes
are connected, wherein
the terminal electrodes and the external electrodes
are arranged in a positional relationship where the direction
of a line connecting the pair of terminal electrodes and the
direction of a line connecting the pair of external electrodes
intersect.
2. The electronic device as set forth in claim 1,
wherein:
a pair of land patterns to which the pair of
terminal electrodes are to be connected are provided on the
front surface of the interposer board, and
these land patterns and external electrodes are
arranged in a positional relationship where the direction of a
line connecting the pair of land patterns and the direction of
the line connecting the pair of external electrodes intersect.
3. The electronic device as set forth in claim 1,
wherein said pair of terminal electrodes in said body and said
interposer board are connected by one of high temperature
solder and a conductive adhesive.
4. The electronic device as set forth in claim 2,
wherein front and back surfaces of said interposer board are
provided with conductor patterns, solder resist is coated on
the surfaces of the conductor patterns to expose at least part
of the surfaces of the conductor patterns, and as a result the
pair of land patterns are formed on the front surface of the
interposer board and the pair of external electrodes are
formed on the back surface of the interposer board.
5. The electronic device as set forth in claim 4,

wherein connecting electrodes connecting the conductor patterns present on the front and back surfaces of the interposer board are provided on the interposer board.

6. The electronic device as set forth in claim 5, wherein said connecting electrodes are through hole electrodes passing through said interposer board.

7. The electronic device as set forth in claim 4, wherein the ends of the interposer board are recessed and the connecting electrodes are arranged in the recessed parts.

8. The electronic device as set forth in claim 1, wherein the electronic device has a plurality of said bodies and the plurality of said bodies are arranged on said interposer board.

9. The electronic device as set forth in claim 1, wherein said body is a multilayer capacitor.

10. An interposer board to a front surface of which a pair of terminal electrodes are to be connected and having on its back surface a pair of external electrodes electrically connected to parts where the pair of terminal electrodes are connected, wherein:

a pair of land patterns to which the pair of terminal electrodes are to be connected are provided on a front surface of said interposer board, and

these land patterns and external electrodes are arranged in a positional relationship where the direction of a line connecting the pair of land patterns and the direction of the line connecting the pair of external electrodes intersect.

11. The interposer board as set forth in claim 10, wherein front and back surfaces of said interposer board are provided with conductor patterns, solder resist is coated on the surfaces of the conductor patterns to expose at least part of the surfaces of the conductor patterns, and as a result the pair of land patterns are formed on the front surface of the interposer board and the pair of external electrodes are formed on the back surface of the interposer board.

12. The interposer board as set forth in claim 11, wherein connecting electrodes connecting the conductor patterns present on the front and back surfaces of the interposer board are provided on the interposer board.

13. The interposer board as set forth in claim 12, wherein said connecting electrodes are through hole electrodes passing through said interposer board.

14. The interposer board as set forth in claim 11, wherein the ends of the interposer board are recessed and the connecting electrodes are arranged in the recessed parts.